

U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)					Docket No. AMAT/3786.Y1/CMP/ CMP/RKK		Serial No. 09/469,709	
<b>SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>					Applicant Li, et al.		Confirmation No. 5296	
(Use several sheets if necessary)					Filing Date December 21, 1999		Group 1763	
Examiner George A. Goudreau								
<b>U.S. Patent Documents</b>								
*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate	
gag	A1	6,001,730 ✓	12/14/1999	Farkas, et al.	438	627	10/20/1997	
	A2	5,994,224 ✓	11/30/1999	Sandhu, et al.	438	692	12/17/1997	
	A3	5,738,574 ✓	04/14/1998	Tolles, et al.	451	288	10/27/1995	
	A4	5,516,346 ✓	05/14/1996	Cadien, et al.	51	308	05/13/1994	
<b>Foreign Patent Documents</b>								
*Examiner Initial		Document Number	Date	Country	<del>Class</del>	<del>Subclass</del>	<del>Translation</del>	
gag	B1	1 085 067 ✓	11/31/1999	EP	<del>G09G</del>	<del>1/02</del>	<del>YES</del>	<del>NO</del>
	B2	1 093 161 ✓	10/11/2000	EP	<del>H01L</del>	<del>24/568</del>	<del>YES</del>	<del>NO</del>
	B3	1 057 591 ✓	12/06/2000	EP	<del>B24B</del>	<del>3/204</del>	<del>YES</del>	<del>NO</del>
	B4	00/35627 ✓	06/22/2000	WO	<del>B24B</del>	<del>3/204</del>	<del>YES</del>	<del>NO</del>
	B5	98/49723 ✓	11/05/1998	WO	<del>H01L</del>	<del>24/521</del>	<del>YES</del>	<del>NO</del>
	B6	00/30154 ✓	05/24/2000	WO	<del>H01L</del>	<del>3/204</del>	<del>YES</del>	<del>NO</del>
	B7	00/59031 ✓	10/05/2000	WO	<del>H01L</del>	<del>24/568</del>	<del>YES</del>	<del>NO</del>
	B8	00/25984 ✓	05/11/2000	WO	<del>B24B</del>	<del>3/204</del>	<del>YES</del>	<del>NO</del>
<b>OTHER ART</b>								
*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.						
gag	C1	European Search Report for 00311569.8 dated November 12, 2003 (AMAT/3786.EP) ✓						
	C2	Peterson, et al., "Investigating CMP and Post-CMP Cleaning Issues for Dual-Damascene Copper Technology" Micro Computerist, Volume 17 No. 1 January 1999 Pages 27-32, 34. ✓						
	C3	Hayashi, et al. "A New Two-Step Metal-CMP Technique for a High Performance Multilevel Interconnects Featured by Al-AND CU in Low Epsilon, Organic Film-Metallizations" 1996 Symposium on VLSI Technology, Digest of Technical Papers Pages 88-89. ✓						
	C4	Schraub, et al., "Chemical Mechanical Polishing: Future Processing Require CMP Tool Flexibility" Proceedings of the SPIE, Volume 3508 September 1998 Pages 146-154 ✓						
	C5	Wijekoon, et al. "Development of a Production Worthy Copper CMP Process" Advanced Semiconductor Manufacturing Conference and Workshop, September 1998, Pages 354-363. ✓						
Examiner George Goudreau					Date Considered 3-04/			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								